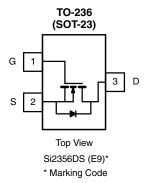




N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I _D (A) ^a	Q _g (Typ.)			
	0.051 at V _{GS} = 10 V	4.3				
40	0.054 at V _{GS} = 4.5 V	4.1	3.8 nC			
	0.070 at V _{GS} = 2.5 V	3.6				



Ordering Information:

Si2356DS-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

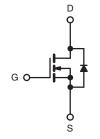
- TrenchFET® Power MOSFET
- 100 % R_q Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



HALOGEN **FREE**

APPLICATIONS

- DC/DC Converter
- Load Switch
- LED Backlighting
- **Power Management**



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	40	V	
Gate-Source Voltage		V _{GS}	± 12	v	
	T _C = 25 °C		4.3		
Continuous Drain Current (T = 150 °C)	T _C = 70 °C		3.4		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	3.2 ^{a,b}		
	T _A = 70 °C		2.6 ^{a,b}	Α	
Pulsed Drain Current (t = 100 μs)		I _{DM}	20		
Continuous Courses Duein Diede Coursest	T _C = 25 °C		1.4		
Continuous Source-Drain Diode Current	T _A = 25 °C	l _S	0.8 ^{a,b}		
	T _C = 25 °C		1.7		
Mariana Barra Birahadia	T _C = 70 °C		1.1		
Maximum Power Dissipation	T _A = 25 °C	P _D	0.96 ^{a,b}	W	
	T _A = 70 °C		0.62 ^{a,b}		
Operating Junction and Storage Temperature	e Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient a,c	t ≤ 5 s	R _{thJA}	100	130	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	60	75				

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s.
- c. Maximum under steady state conditions is 175 $^{\circ}\text{C/W}.$

Document Number: 62893 S13-1814-Rev. A, 12-Aug-13 For technical questions, contact: pmostechsupport@vishav.com



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		43		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 3.8			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	0.6		1.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
		V _{DS} = 40 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α	
		$V_{GS} = 10 \text{ V}, I_D = 3.2 \text{ A}$		0.042	0.051	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 3.1 \text{ A}$		0.045	0.054		
		$V_{GS} = 2.5 \text{ V}, I_D = 2 \text{ A}$		0.056	0.070		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 3.2 A		13		S	
Dynamic ^b	l		L		I .		
Input Capacitance	C _{iss}			370			
Output Capacitance	C _{oss}	V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz		50		pF	
Reverse Transfer Capacitance	C _{rss}			17			
	Q _g	V _{DS} = 20 V, V _{GS} = 10 V, I _D = 3.2 A		8.1	13	nC	
Total Gate Charge			-	3.8	5.7		
Gate-Source Charge	Q_{gs}	Q_{gs} $V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.2 \text{ A}$		0.72			
Gate-Drain Charge	Q_{gd}			0.81			
Gate Resistance	Rg	f = 1 MHz	0.2	0.7	1.4	Ω	
Turn-On Delay Time	t _{d(on)}			6	12		
Rise Time	t _r	$V_{DD} = 20 \text{ V}, R_{L} = 7.7 \Omega$		12	20	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 2.6 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		13	20		
Fall Time	t _f			6	12	1	
Turn-On Delay Time	t _{d(on)}			10	20	ns	
Rise Time	t _r	$V_{DD} = 20 \text{ V}, R_L = 7.7 \Omega$ $I_D \cong 2.6 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		52	78		
Turn-Off Delay Time	t _{d(off)}			18	27		
Fall Time	t _f			53	80	1	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			1.4	^	
Pulse Diode Forward Current (t = 100 μs)	I _{SM}				20	A	
Body Diode Voltage	V _{SD}	I _S = 2.6 A, V _{GS} = 0 V		0.8	1.2	٧	
Body Diode Reverse Recovery Time	t _{rr}			12	20	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L _ 0.6.4 dl/dt _ 100.4/::2 T _ 05.90		5	10	nC	
Reverse Recovery Fall Time	t _a	$I_F = 2.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		8.5		ns	
Reverse Recovery Rise Time	t _b			3.5			

Notes:

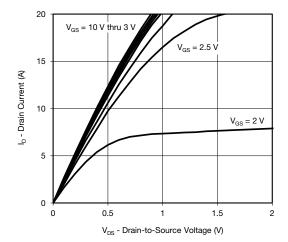
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

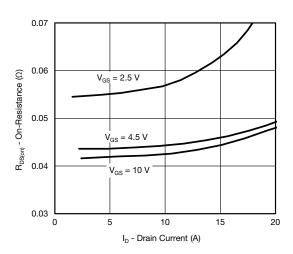
b. Guaranteed by design, not subject to production testing.



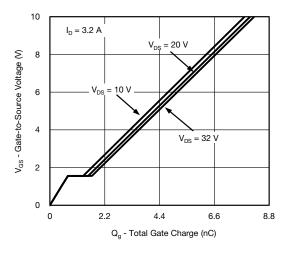
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



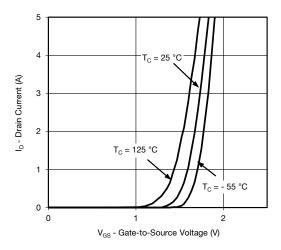
Output Characteristics



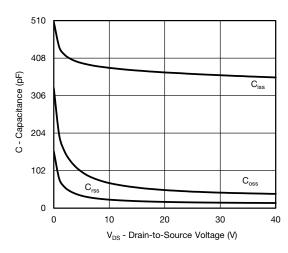
On-Resistance vs. Drain Current and Gate Voltage



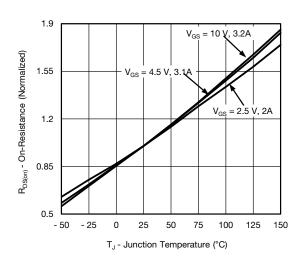
Gate Charge



Transfer Characteristics

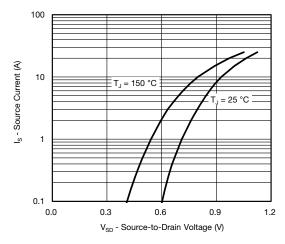


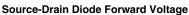
Capacitance

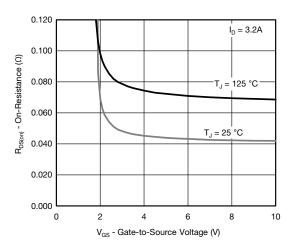


On-Resistance vs. Junction Temperature

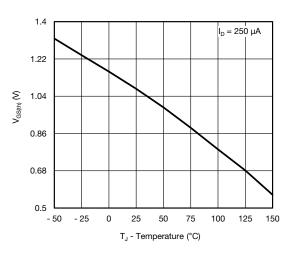
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



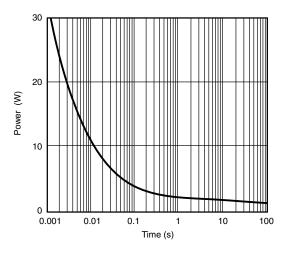




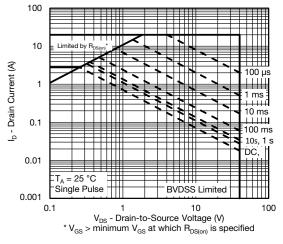
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



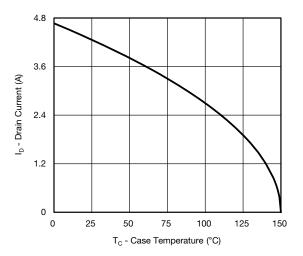
Single Pulse Power (Junction-to-Ambient)



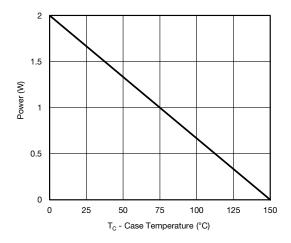
Safe Operating Area, Junction-to-Ambient

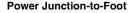


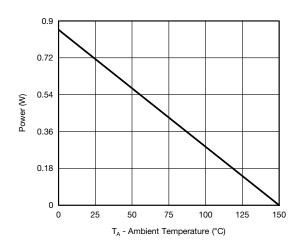
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*



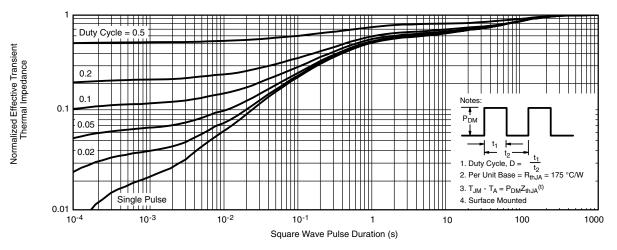




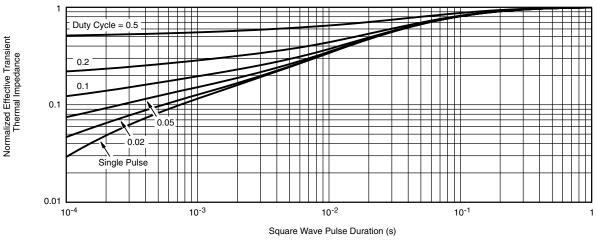
Power Junction-to-Ambient

 $^{^{\}star}$ The power dissipation P_D is based on $T_{J(max.)}$ = 150 $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heats inking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOT-23 (TO-236): 3-LEAD







Dim	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.9	5 BSC	C 0.0374		
e ₁	1.9	0 BSC	0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	lul-01	•			

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479

Document Number: 71196 www.vishay.com 09-Jul-01



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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